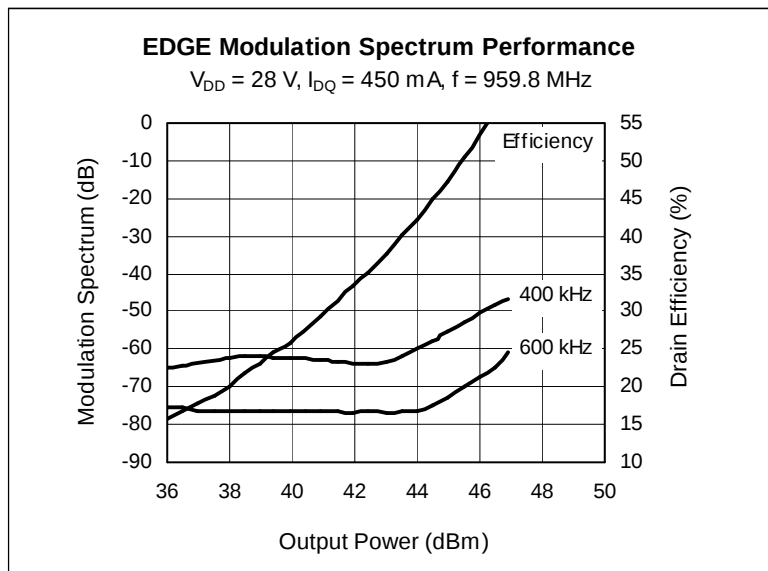




## LDMOS RF Power Field Effect Transistor 45 W, 869–960 MHz

### Description

The PTF080451 is a 45 W, internally matched *GOLDMOS* FET intended for EDGE and CDMA applications in the 860 to 960 MHz band. Full gold metallization ensures excellent device lifetime and reliability.



### Features

- Broadband internal matching
- Typical EDGE performance
  - Average output power = 22.5 W
  - Gain = 18 dB
  - Efficiency = 40%
- Typical CW performance
  - Output power at P-1dB = 60 W
  - Gain = 17 dB
  - Efficiency = 60%
- Integrated ESD protection: Human Body Model, Class 1 (minimum)
- Excellent thermal stability
- Low HCI drift
- Capable of handling 10:1 VSWR @ 28 V, 45 W (CW) output power



PTF080451E  
Package 30265

**ESD:** Electrostatic discharge sensitive device—observe handling precautions!

### RF Characteristics at $T_{CASE} = 25^{\circ}\text{C}$ unless otherwise indicated

**EDGE Measurements** (not subject to production test—verified by design/characterization in Infineon test fixture)

$V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 450\text{ mA}$ ,  $P_{OUT} = 22.5\text{ W}$ ,  $f = 959.8\text{ MHz}$

| Characteristic                | Symbol    | Min | Typ | Max | Units |
|-------------------------------|-----------|-----|-----|-----|-------|
| Error Vector Magnitude        | EVM (RMS) | —   | 2.0 | —   | %     |
| Modulation Spectrum @ 400 kHz | ACPR      | —   | -62 | —   | dBc   |
| Modulation Spectrum @ 600 kHz | ACPR      | —   | -76 | —   | dBc   |
| Gain                          | $G_{ps}$  | —   | 18  | —   | dB    |
| Drain Efficiency              | $\eta_D$  | —   | 40  | —   | %     |

**Two-Tone Measurements** (tested in Infineon test fixture)

$V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 450\text{ mA}$ ,  $P_{OUT} = 45\text{ W PEP}$ ,  $f = 960\text{ MHz}$ , tone spacing = 1 MHz

| Characteristic             | Symbol   | Min | Typ | Max | Units |
|----------------------------|----------|-----|-----|-----|-------|
| Gain                       | $G_{ps}$ | 17  | 18  | —   | dB    |
| Drain Efficiency           | $\eta_D$ | 40  | 42  | —   | %     |
| Intermodulation Distortion | IMD      | —   | -32 | -30 | dBc   |

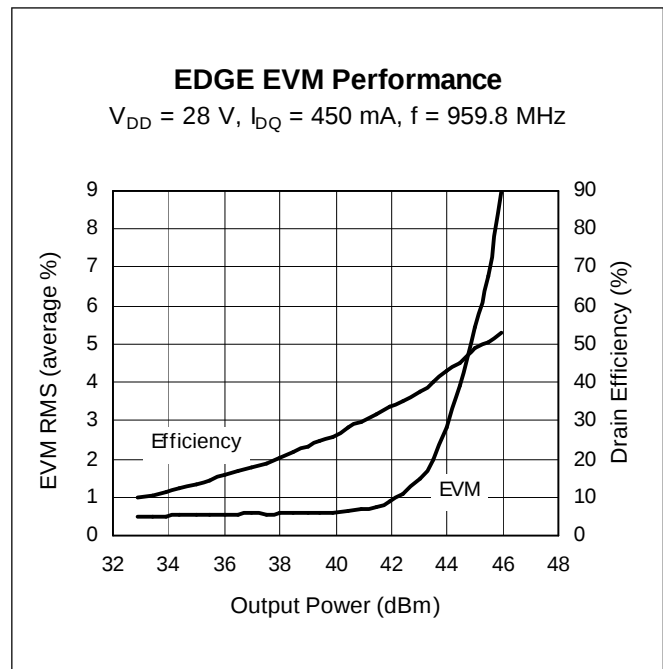
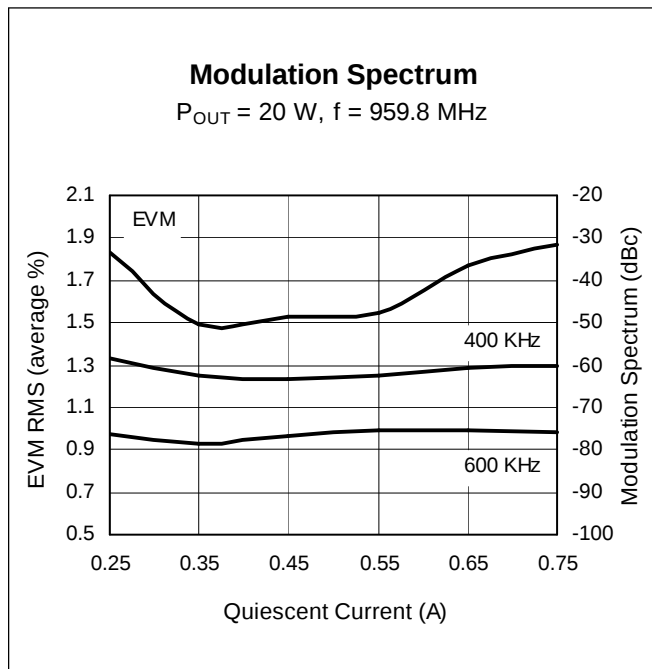
## DC Characteristics at $T_{CASE} = 25^{\circ}C$ unless otherwise indicated

| Characteristic                 | Conditions                                            | Symbol        | Min | Typ | Max | Units         |
|--------------------------------|-------------------------------------------------------|---------------|-----|-----|-----|---------------|
| Drain–Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_{DS} = 10\text{ }\mu\text{A}$ | $V_{(BR)DSS}$ | 65  | —   | —   | V             |
| Drain Leakage Current          | $V_{DS} = 28\text{ V}, V_{GS} = 0\text{ V}$           | $I_{DSS}$     | —   | —   | 1.0 | $\mu\text{A}$ |
| On–State Resistance            | $V_{GS} = 10\text{ V}, V_{DS} = 0.1\text{ V}$         | $R_{DS(on)}$  | —   | 0.1 | —   | $\Omega$      |
| Operating Gate Voltage         | $V_{DS} = 28\text{ V}, I_{DQ} = 450\text{ mA}$        | $V_{GS}$      | 2.5 | 3.2 | 4   | V             |
| Gate Leakage Current           | $V_{GS} = 10\text{ V}, V_{DS} = 0\text{ V}$           | $I_{GSS}$     | —   | —   | 1.0 | $\mu\text{A}$ |

## Maximum Ratings

| Parameter                                                 | Symbol          | Value       | Unit                |
|-----------------------------------------------------------|-----------------|-------------|---------------------|
| Drain–Source Voltage                                      | $V_{DSS}$       | 65          | V                   |
| Gate–Source Voltage                                       | $V_{GS}$        | –0.5 to +12 | V                   |
| Junction Temperature                                      | $T_J$           | 200         | $^{\circ}C$         |
| Total Device Dissipation<br>Above $25^{\circ}C$ derate by | $P_D$           | 184<br>1.05 | W<br>W/ $^{\circ}C$ |
| Storage Temperature Range                                 | $T_{STG}$       | –40 to +150 | $^{\circ}C$         |
| Thermal Resistance ( $T_{CASE} = 70^{\circ}C$ )           | $R_{\theta JC}$ | 0.95        | $^{\circ}C/W$       |

## Typical Performance (measurements taken in production test fixture)

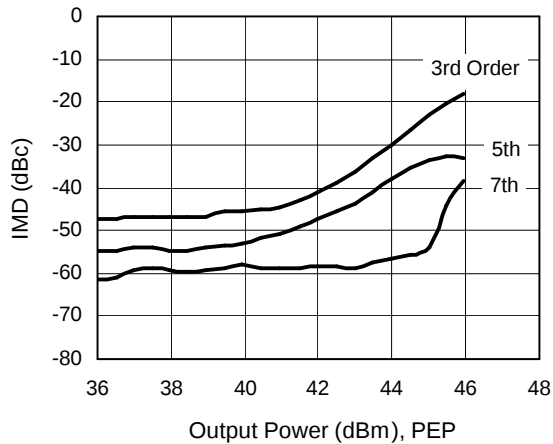


All published data at  $T_{CASE} = 25^{\circ}C$  unless otherwise indicated.

## Typical Performance (cont.)

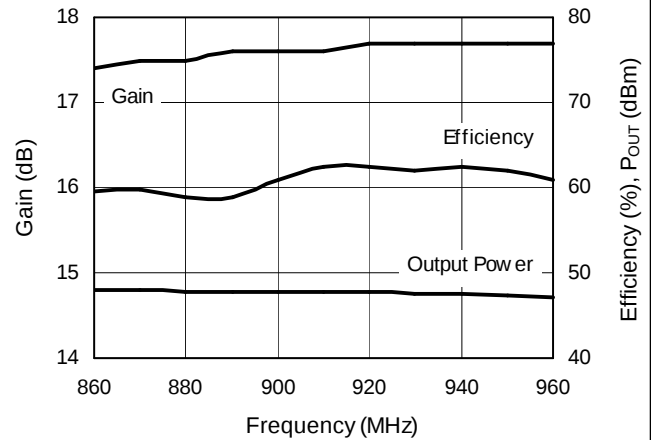
### Intermodulation Distortion vs. Output Power (as measured in a broadband circuit)

$V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 450\text{ mA}$ ,  $f_1 = 959\text{ MHz}$ ,  $f_2 = 960\text{ MHz}$



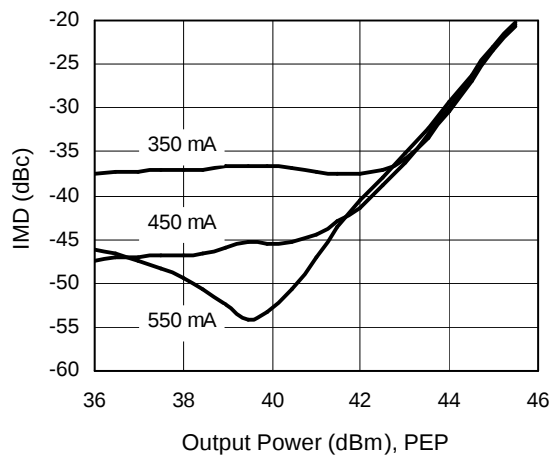
### Typical $P_{OUT}$ , Gain & Efficiency (at P-1dB) vs. Frequency

$V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 450\text{ mA}$



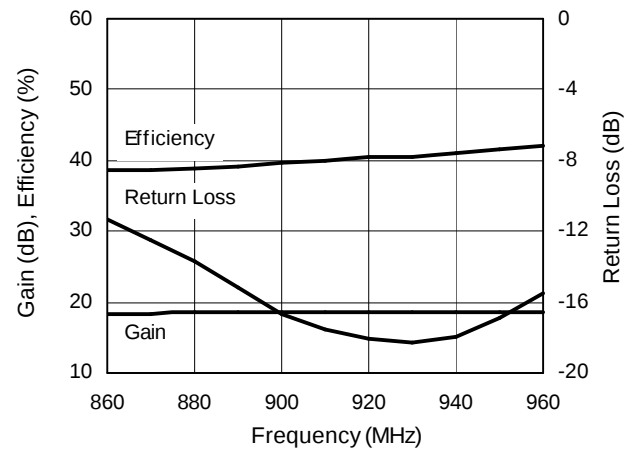
### IM3 vs. Output Power at Selected Biases

$V_{DD} = 28\text{ V}$ ,  $f_1 = 959\text{ MHz}$ ,  $f_2 = 960\text{ MHz}$



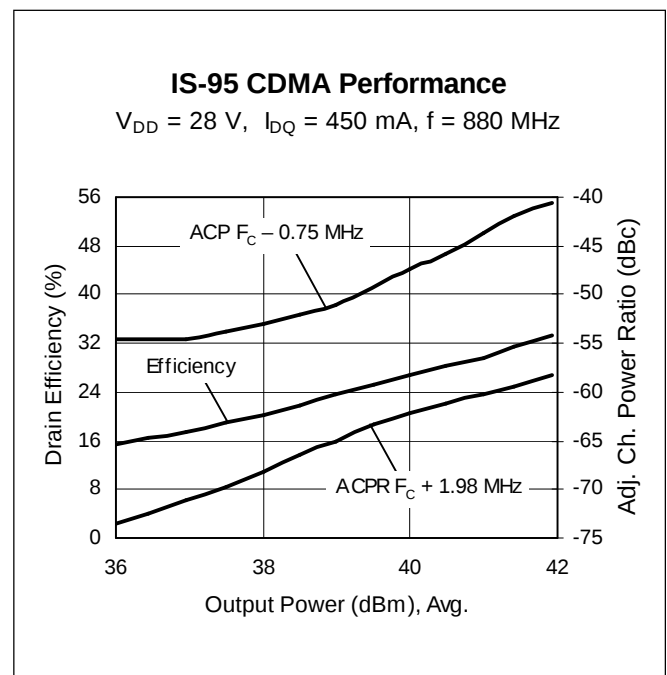
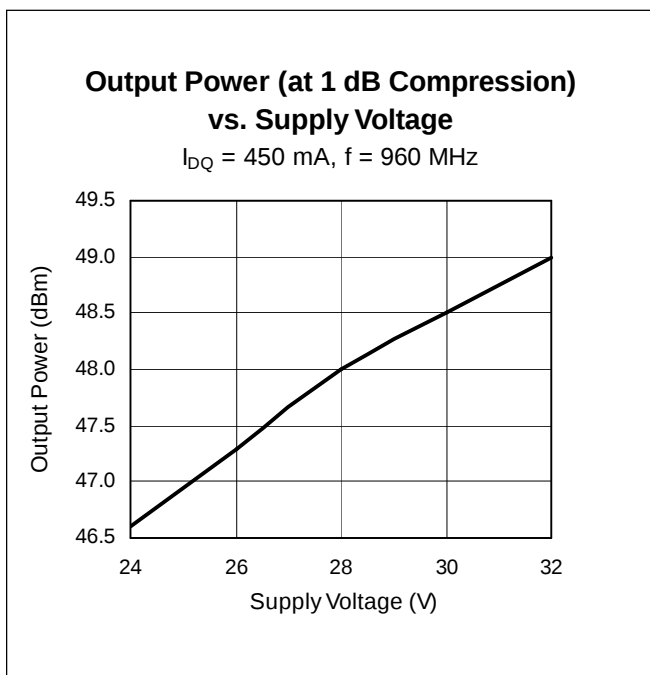
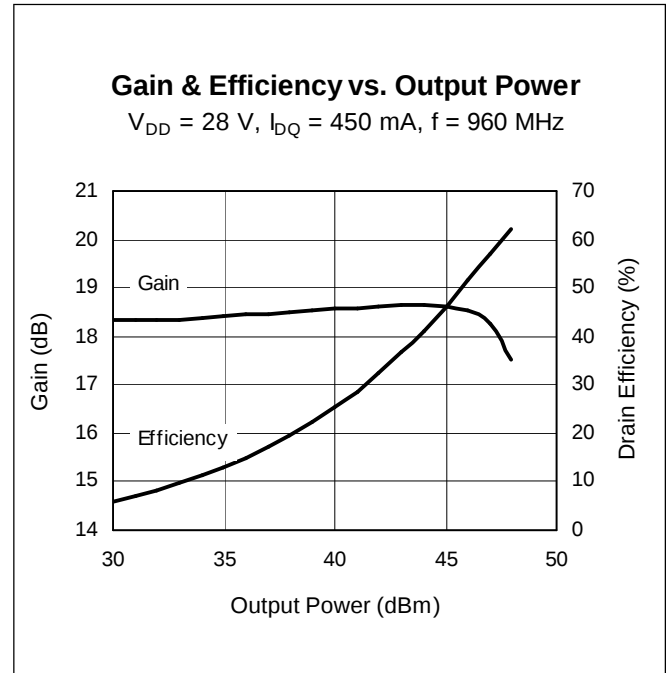
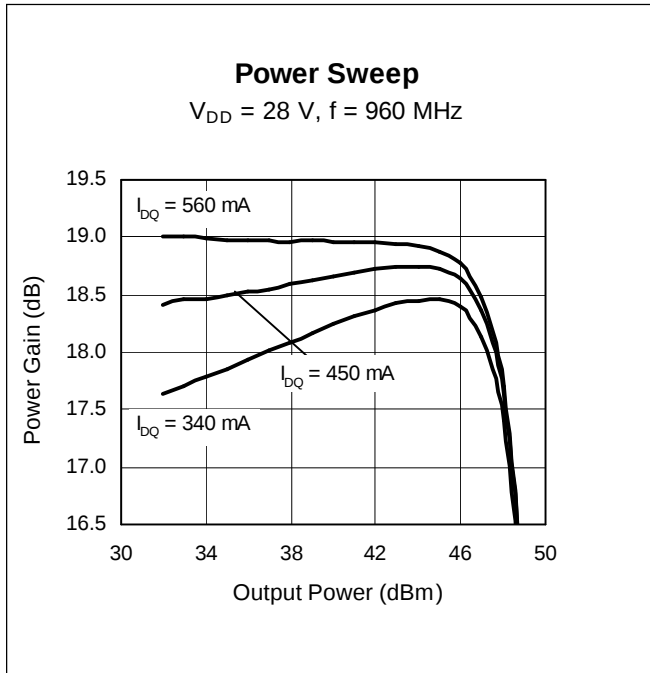
### Broadband Performance

$V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 450\text{ mA}$ ,  $P_{OUT} = 22.5\text{ W}$



All published data at  $T_{CASE} = 25^\circ\text{C}$  unless otherwise indicated.

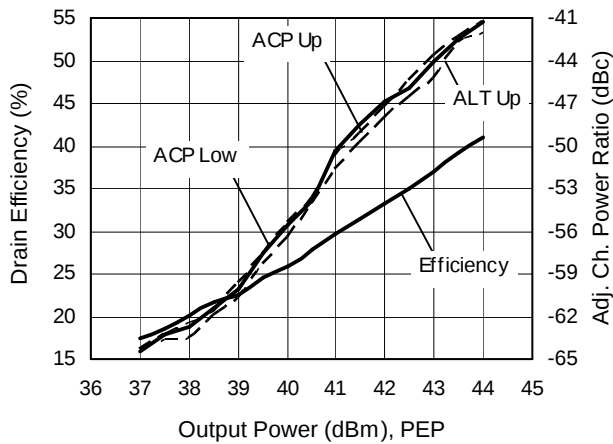
## Typical Performance (cont.)



All published data at  $T_{CASE} = 25^\circ\text{C}$  unless otherwise indicated.

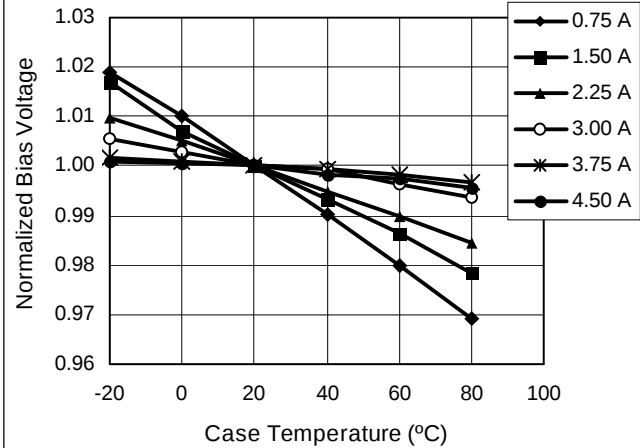
## Typical Performance (cont.)

### Three-Carrier CDMA 2000 Performance

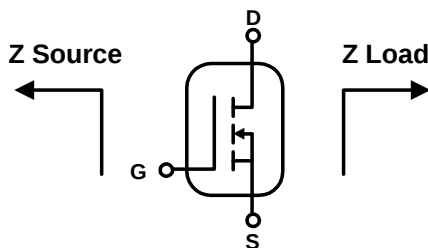
 $V_{DD} = 28 \text{ V}$ ,  $I_{DQ} = 450 \text{ mA}$ ,  $f = 880 \text{ MHz}$ 


### Bias Voltage vs. Temperature

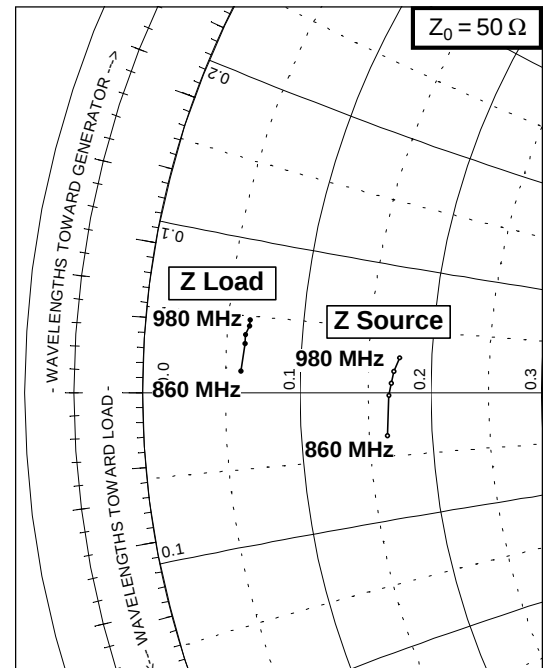
Voltage normalized to typical gate voltage.  
Series show current.



## Broadband Circuit Impedance

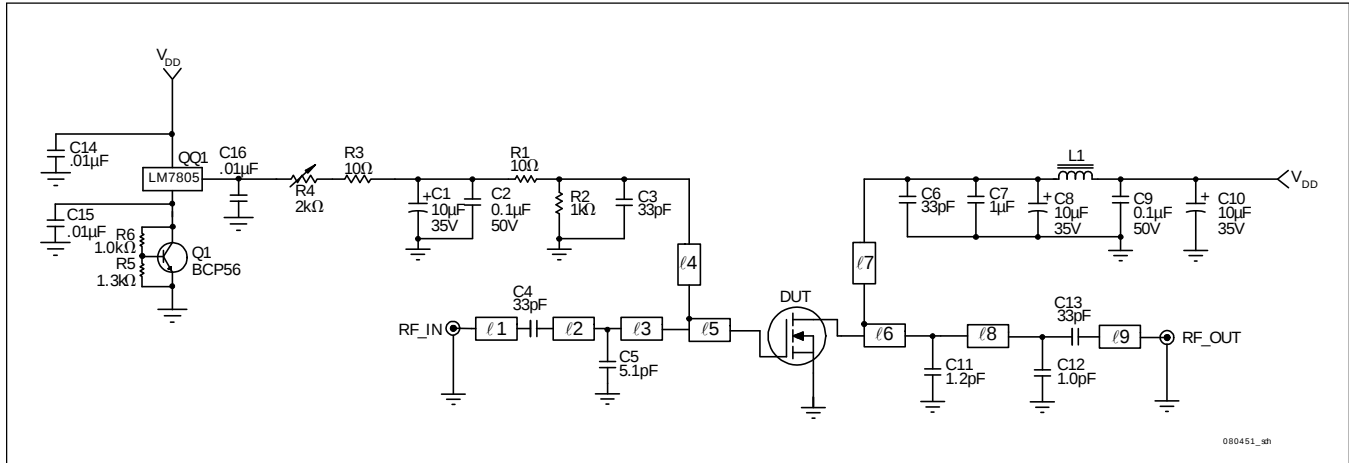


| Frequency<br>MHz | Z Source $\Omega$ |       | Z Load $\Omega$ |      |
|------------------|-------------------|-------|-----------------|------|
|                  | R                 | jX    | R               | jX   |
| 860              | 8.20              | -1.70 | 3.00            | 0.70 |
| 920              | 8.30              | -0.12 | 3.10            | 1.60 |
| 940              | 8.40              | 0.38  | 3.10            | 1.90 |
| 960              | 8.50              | 0.85  | 3.20            | 2.20 |
| 980              | 8.70              | 1.40  | 3.20            | 2.40 |



All published data at  $T_{CASE} = 25^\circ\text{C}$  unless otherwise indicated.

## Test Circuit



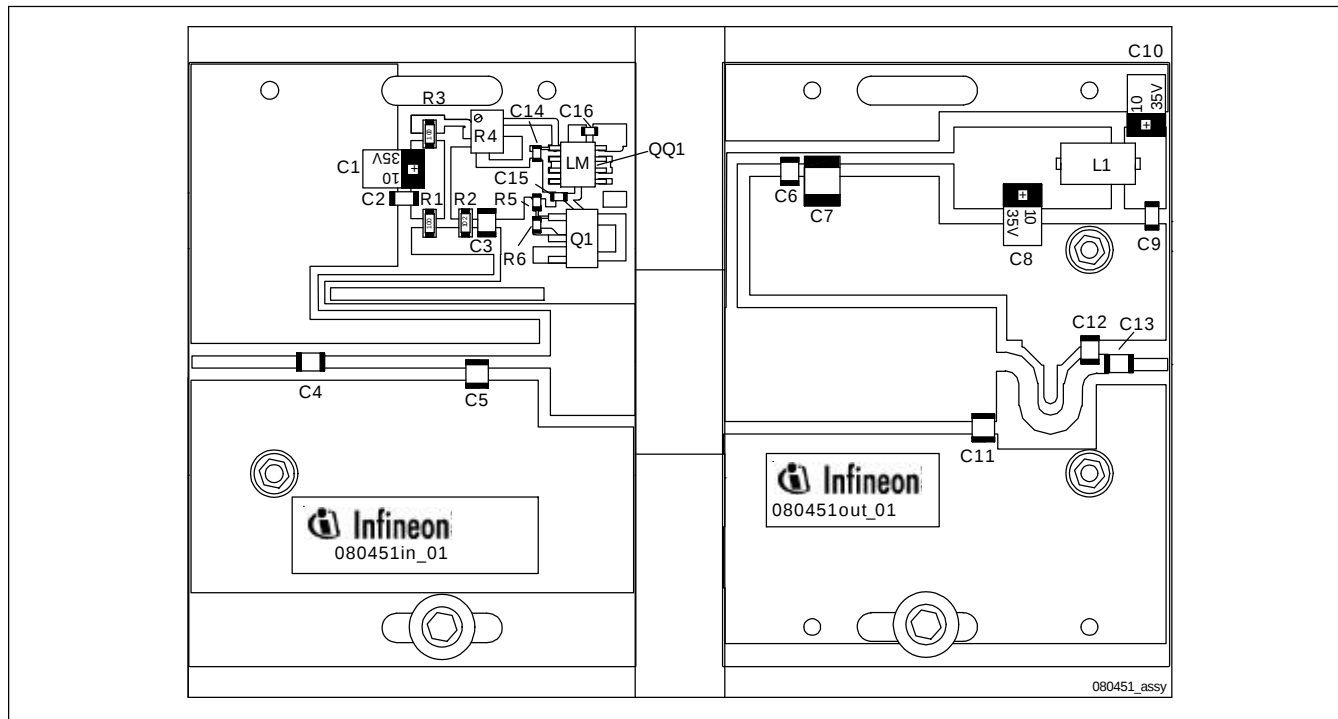
Test Circuit Schematic for 960 MHz

### Circuit Assembly Information

|     |                                            |                  |             |
|-----|--------------------------------------------|------------------|-------------|
| DUT | PTF080451                                  | LDMOS Transistor |             |
| PCB | 0.76 mm. [.030"] thick, $\epsilon_r = 4.5$ | 2 oz. copper     | Rogers TMM4 |

| Microstrip | Electrical Characteristics at 960 MHz | Dimensions: L x W (mm.) | Dimensions: L x W (in.) |
|------------|---------------------------------------|-------------------------|-------------------------|
| $\ell1$    | 0.075 $\lambda$ , 50.770 $\Omega$     | 0.505 x 0.053           | 12.83 x 1.35            |
| $\ell2$    | 0.114 $\lambda$ , 50.770 $\Omega$     | 0.765 x 0.053           | 19.43 x 1.35            |
| $\ell3$    | 0.050 $\lambda$ , 50.770 $\Omega$     | 0.335 x 0.053           | 8.51 x 1.35             |
| $\ell4$    | 0.289 $\lambda$ , 73.660 $\Omega$     | 2.000 x 0.025           | 50.80 x 0.64            |
| $\ell5$    | 0.060 $\lambda$ , 9.350 $\Omega$      | 0.360 x 0.506           | 9.14 x 12.85            |
| $\ell6$    | 0.199 $\lambda$ , 9.190 $\Omega$      | 1.200 x 0.510           | 30.48 x 12.95           |
| $\ell7$    | 0.132 $\lambda$ , 52.470 $\Omega$     | 0.890 x 0.050           | 22.61 x 1.27            |
| $\ell8$    | 0.134 $\lambda$ , 38.020 $\Omega$     | 0.880 x 0.085           | 22.35 x 2.16            |
| $\ell9$    | 0.029 $\lambda$ , 50.200 $\Omega$     | 0.195 x 0.054           | 4.95 x 1.37             |

## Test Circuit (cont.)



Reference Circuit<sup>1</sup> (not to scale)

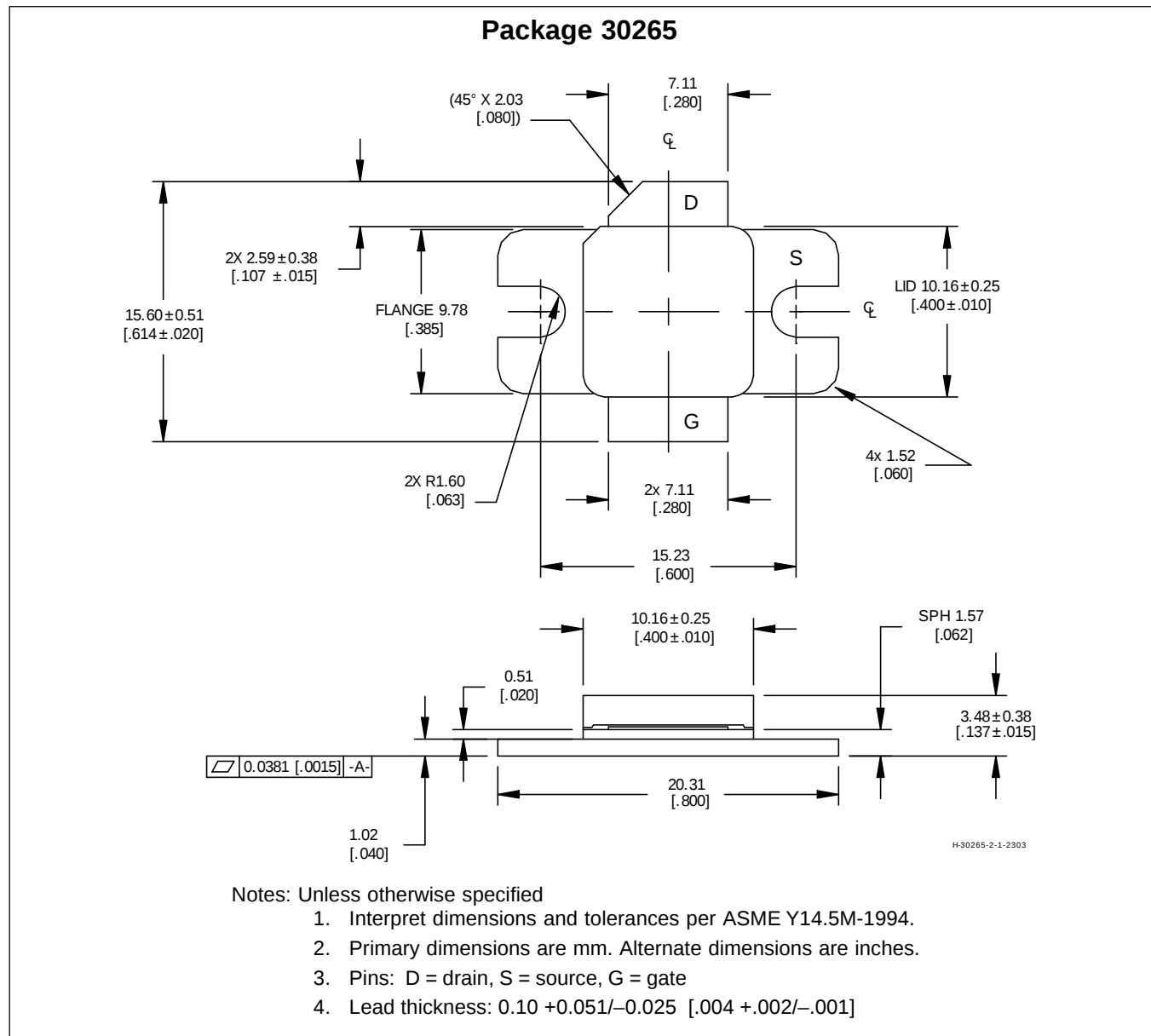
| Component       | Description                                     | Manufacturer | P/N or Comment   |
|-----------------|-------------------------------------------------|--------------|------------------|
| C1, C8, C10     | Capacitor, 10 $\mu$ F, 35 V, Tant TE Series SMD | Digi-Key     | PCS6106TR-ND     |
| C2, C9          | Capacitor, 0.1 $\mu$ F, 50 V                    | Digi-Key     | P4525-ND         |
| C3, C4, C6, C13 | Capacitor, 33 pF                                | ATC          | 100B 330         |
| C5              | Capacitor, 5.1 pF                               | ATC          | 100B 5R1         |
| C7              | Capacitor, 1 $\mu$ F, 50 V                      | Digi-Key     | 19528-ND         |
| C11             | Capacitor, 1.2 pF                               | ATC          | 100B 1R2         |
| C12             | Capacitor, 1.0 pF                               | ATC          | 100B 1R0         |
| C14, C15, C16   | Capacitor, .01 $\mu$ F                          | Digi-Key     | PCC1772CT-ND     |
| L1              | Ferrite, 6 mm                                   | Philips      | 53/3/4.6-452     |
| Q1              | Transistor                                      | Infineon     | BCP56            |
| QQ1             | Voltage Regulator                               | Digi-Key     | LM7805           |
| R1, R3          | Resistor, 10 ohm                                | Digi-Key     | 100ECT-ND        |
| R2              | Resistor, 1.0 k-ohm                             | Digi-Key     | 1KQBK            |
| R4              | Resistor, Variable 2 k-ohm, 4 W                 | Digi-Key     | 3224 W-202ETR-ND |
| R5              | Resistor, 1.3 k-ohm 1/10 W, 0603                | Digi-Key     | P1.3KGCT-ND      |
| R6              | Resistor, 1.0 k-ohm 1/10 W, 0603                | Digi-Key     | P1.0KGCT-ND      |

<sup>1</sup>Gerber files for this circuit are available on request.

## Ordering Information

| Type       | Package Outline | Package Description              | Marking    |
|------------|-----------------|----------------------------------|------------|
| PTF080451E | 30265           | Thermally enhanced, flange mount | PTF080451E |

## Package Outline Specifications



Find the latest and most complete information about products and packaging at the Infineon Internet page  
<http://www.infineon.com/products>

**Revision History: 2004-06-24**

Data Sheet

Previous Version: 2003-11-04, Developmental Data Sheet

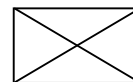
| Page | Subjects (major changes since last revision) |
|------|----------------------------------------------|
| all  | Include further data                         |
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